



#### Product Summary

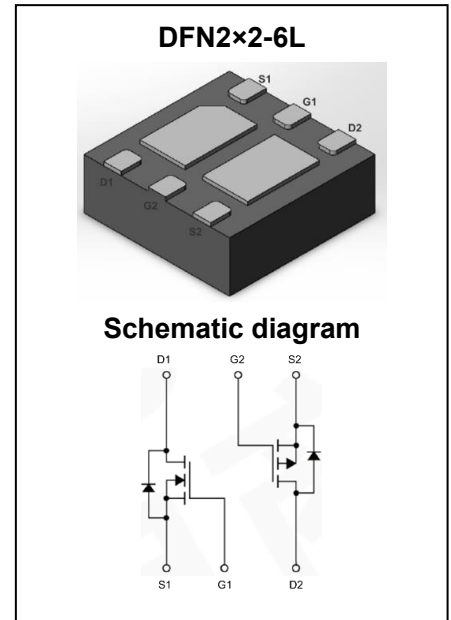
V <sub>(BR)DSS</sub>	R <sub>DS(on)TYP</sub>	I <sub>D</sub>
30V	30mΩ@10V	3.16A
	40mΩ@4.5V	
-30V	55mΩ@-10V	-2.7A
	75mΩ@-4.5V	

#### Feature

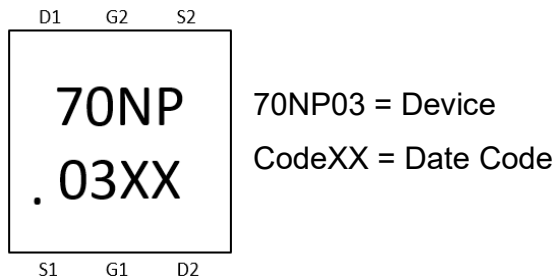
- Trench Technology Power MOSFET
- Low R<sub>DS(ON)</sub>
- Low Gate Charge

#### Application

- Load Switch
- DC/DC Converter



#### MARKING:



#### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Value	Value	Unit
Drain - Source Voltage	V <sub>DS</sub>	30	-30	V
Gate - Source Voltage	V <sub>GS</sub>	±20	±20	V
Continuous Drain Current <sup>1,5</sup>	I <sub>D</sub>	3.16	-2.7	A
T <sub>A</sub> = 25°C				
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	12.6	10.8	A
Power Dissipation <sup>4,5</sup>	P <sub>D</sub>	1.8	1.8	W
T <sub>A</sub> = 25°C				
Thermal Resistance from Junction to Ambient <sup>5</sup>	R <sub>θJA</sub>	69	69	°C/W
Junction Temperature	T <sub>J</sub>	150	150	°C
Storage Temperature	T <sub>STG</sub>	-55~ +150	-55~ +150	°C

## MOSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

### NMOS:

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$			1	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.6	3	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 4A$		30	45	m $\Omega$
		$V_{GS} = 4.5V, I_D = 4A$		40	80	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$		293		pF
Output Capacitance	$C_{oss}$			40		
Reverse Transfer Capacitance	$C_{rss}$			34		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		1.4		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = 15V, V_{GS} = 10V, I_D = 4A$		7.7		nC
Gate-source Charge	$Q_{gs}$			1.2		
Gate-drain Charge	$Q_{gd}$			1.7		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 15V, V_{GS} = 10V,$ $R_L = 7.5\Omega, R_G = 3\Omega$		3		ns
Turn-on Rise Time	$t_r$			4		
Turn-off Delay Time	$t_{d(off)}$			23		
Turn-off Fall Time	$t_f$			7		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 1.67A$			1.2	V

## OSFET ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

### PMOS:

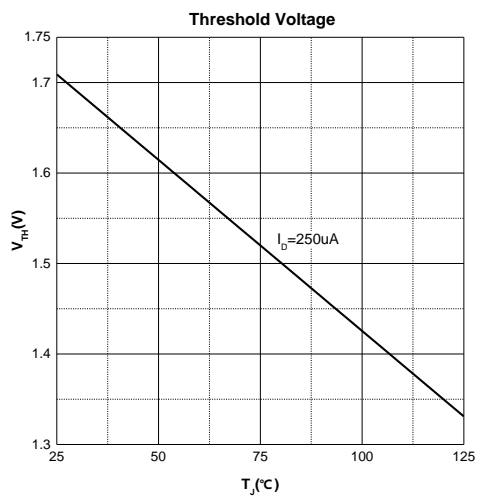
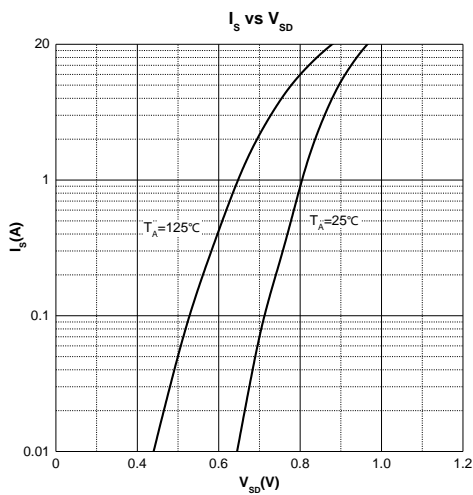
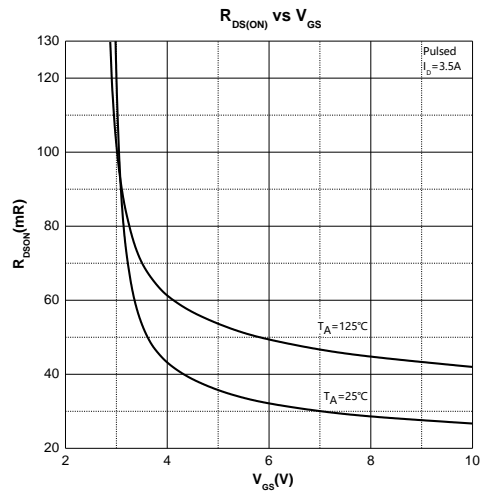
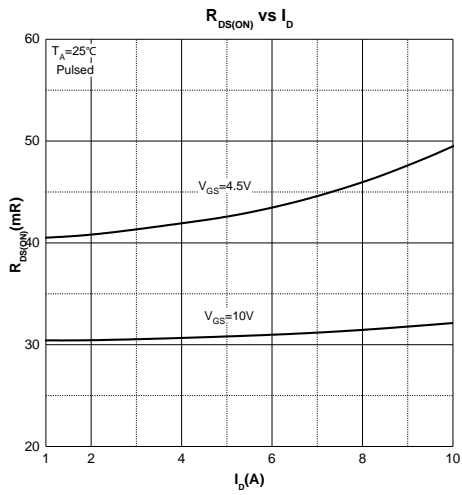
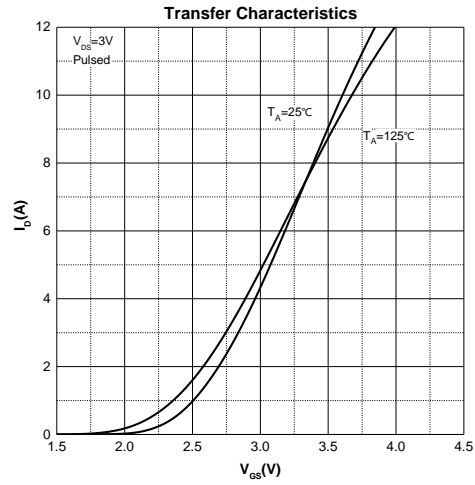
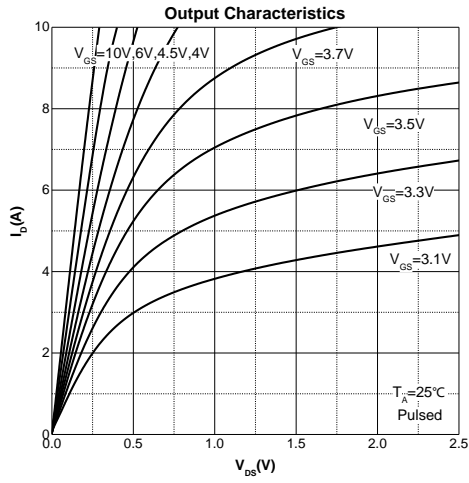
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -30V, V_{GS} = 0V$			-1	$\mu A$
Gate - Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 100$	nA
<b>On Characteristics<sup>3</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.5	-3	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -4A$		62	78	m $\Omega$
		$V_{GS} = -4.5V, I_D = -4A$		89	140	
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$		304		pF
Output Capacitance	$C_{oss}$			49		
Reverse Transfer Capacitance	$C_{rss}$			40		
Gate Resistance	$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		5.4		$\Omega$
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DS} = -15V, V_{GS} = -10V, I_D = -4A$		9.0		nC
Gate-source Charge	$Q_{gs}$			1.7		
Gate-drain Charge	$Q_{gd}$			2.6		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -15V, V_{GS} = -10V,$ $R_L = 1.8\Omega, R_G = 3\Omega$		8		ns
Turn-on Rise Time	$t_r$			6		
Turn-off Delay Time	$t_{d(off)}$			26		
Turn-off Fall Time	$t_f$			12		
<b>Source - Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = -1.67A$			-1.2	V

### Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$ .
- 3.Pulse Test : Pulse Width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 4.The power dissipation  $P_D$  is limited by  $T_{J(MAX)} = 150^\circ\text{C}$ .
- 5.Device mounted on  $1in^2$  FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .

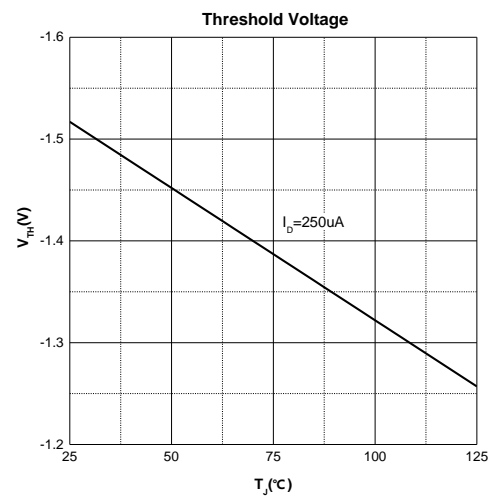
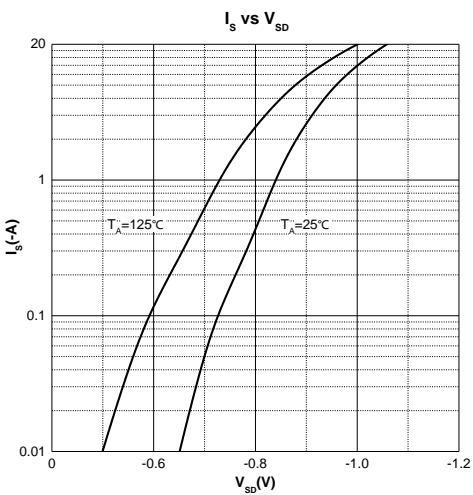
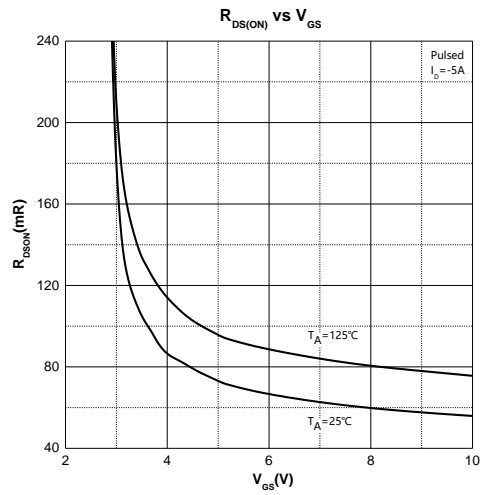
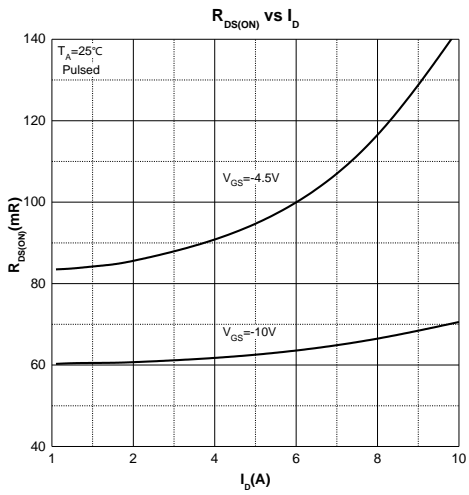
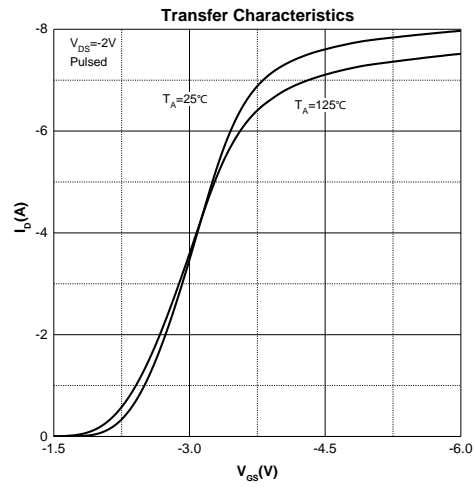
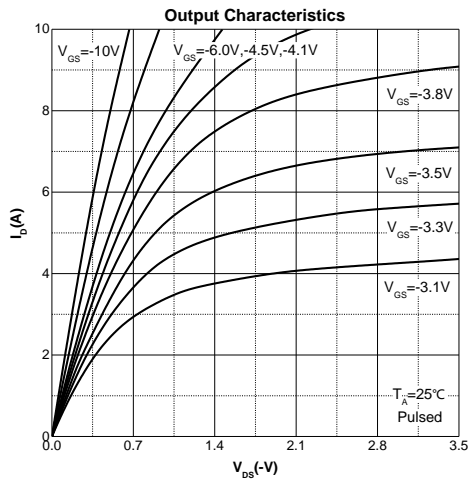
**Typical Characteristics**

**NMOS:**

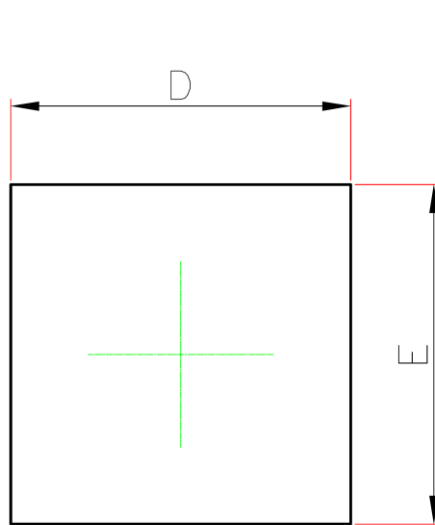


## Typical Characteristics

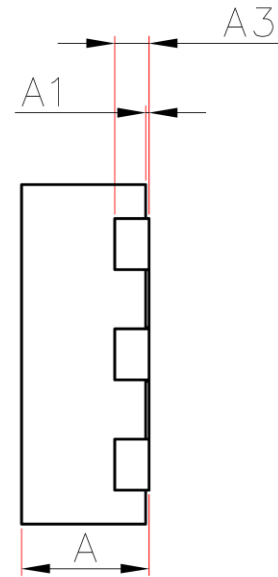
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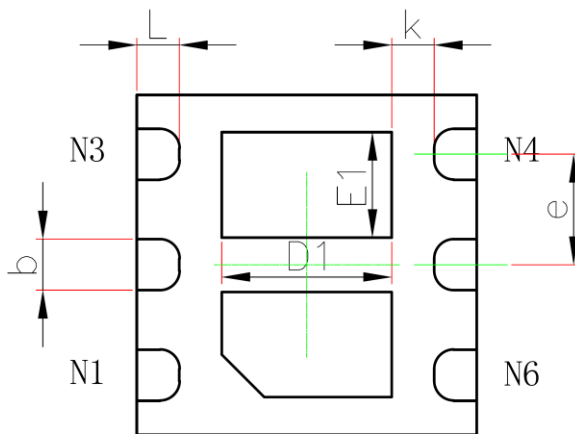
## DFN2×2-6L Package Information



TOP VIEW



SIDE VIEW



BOTTOM VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0	0.050	0	0.002
A3	2.03REF		0.008REF	
D	1.900	2.100	0.075	0.083
E	1.900	2.100	0.075	0.083
D1	0.900	1.100	0.035	0.043
E1	0.520	0.720	0.020	0.028
k	0.200MIN		0.008MIN	
b	0.250	0.350	0.010	0.014
e	0.65BSC		0.026TYP	
L	0.174	0.326	0.007	0.013